# Low VCE(sat) Transistor, NPN, 60 V, 6.0 A

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

## **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*
- Complementary to NSS60600MZ4

## **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	60	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	100	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current - Continuous	Ic	6.0	Α
Collector Current - Peak	I <sub>CM</sub>	12.0	Α

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



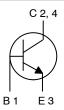
## ON Semiconductor®

http://onsemi.com

60 VOLTS, 6.0 AMPS 2.0 WATTS NPN LOW  $V_{CE(sat)}$  TRANSISTOR EQUIVALENT  $R_{DS(on)}$  50 m $\Omega$ 



SOT-223 CASE 318E STYLE 1



**Schematic** 

## MARKING DIAGRAM



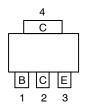
A = Assembly Location

Y = Year

W = Work Week 60601 = Specific Device Code

= Pb-Free Package

## **PIN ASSIGNMENT**



Top View Pinout

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	155	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	2 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS60601MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSV60601MZ4T1G*	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSS60601MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel
NSV60601MZ4T3G*	SOT-223 (Pb-Free)	4,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
\*NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP

<sup>1.</sup> FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces. 2. FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.

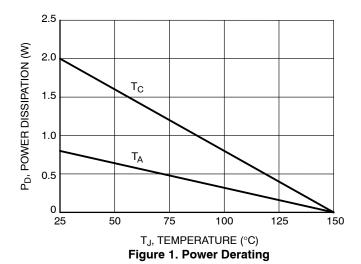
<sup>3.</sup> Thermal response.

Capable.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Min	Тур	Max	Unit
V <sub>(BR)CEO</sub>	60	-	_	Vdc
V <sub>(BR)CBO</sub>	100	-	-	Vdc
V <sub>(BR)EBO</sub>	6.0	-	_	Vdc
I <sub>CBO</sub>	_	-	0.1	μAdc
I <sub>EBO</sub>	_	-	0.1	μAdc
h <sub>FE</sub>	150 120 100 50	- - - -	- 360 - -	-
V <sub>CE(sat)</sub>	- - - -	- 0.045 0.085 - -	0.040 0.060 0.100 0.220 0.300	V
V <sub>BE(sat)</sub>	_	-	0.900	٧
V <sub>BE(on)</sub>	=	-	0.900	V
f <sub>T</sub>	100	-	-	MHz
Cibo	-	400	-	pF
Cobo	-	37	-	pF
t <sub>d</sub>	-	85	-	ns
t <sub>r</sub>	-	115	-	ns
to	_	1350	_	ns
-5				
	V(BR)CEO V(BR)CBO V(BR)EBO ICBO IEBO VCE(sat) VBE(sat) VBE(on) fT Cibo Cobo	V(BR)CEO         60           V(BR)CBO         100           V(BR)EBO         6.0           ICBO         -           IEBO         -      VCE(sat)	V(BR)CEO         60         -           V(BR)CBO         100         -           V(BR)EBO         6.0         -           ICBO         -         -           IEBO         -         -           NFE         150         -           120         -         -           100         -         -           NCE(sat)         -         -           NBE(sat)         -         -           VBE(on)         -         -           Tobo         -         400           Cobo         -         37	V(BR)CEO         60         -         -           V(BR)CBO         100         -         -           V(BR)EBO         6.0         -         -           ICBO         -         -         0.1           IEBO         -         -         0.1           hFE         150         -         -           120         -         360           100         -         -           VCE(sat)         -         -           -         0.045         0.060           -         0.220           -         -         0.300           VBE(sat)         -         -         0.900           VBE(on)         -         -         0.900           fT         100         -         -           Cobo         -         37         -           td         -         85         -           td         -         115         -

<sup>4.</sup> Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq$  2%.



## **TYPICAL CHARACTERISTICS**

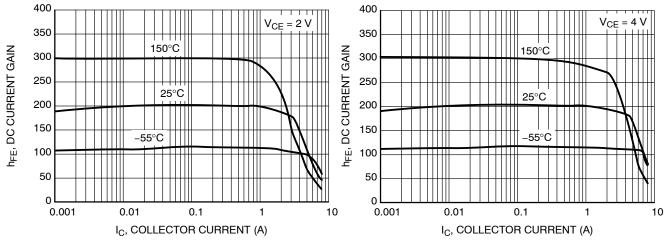


Figure 2. DC Current Gain

Figure 3. DC Current Gain

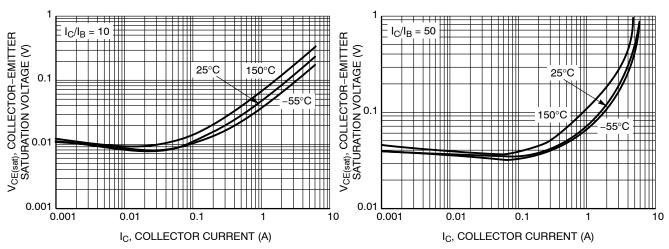


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage

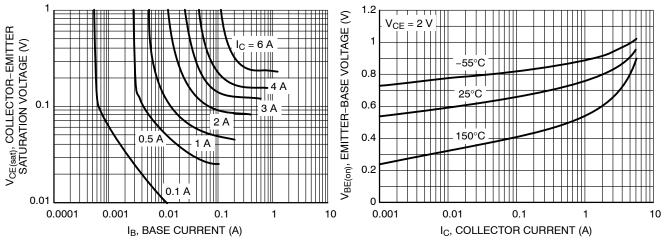
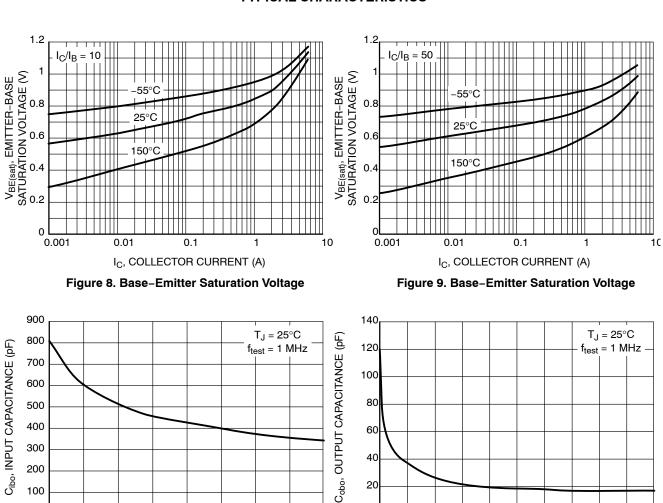


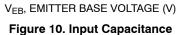
Figure 6. Collector Saturation Region

Figure 7. V<sub>BE(on)</sub> Voltage

## **TYPICAL CHARACTERISTICS**



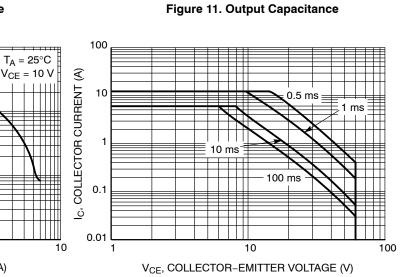
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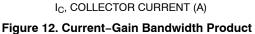
0.001

0.01

f<sub>Tau</sub>, CURRENT BANDWIDTH PRODUCT (MHz)



V<sub>CB</sub>, COLLECTOR BASE VOLTAGE (V)

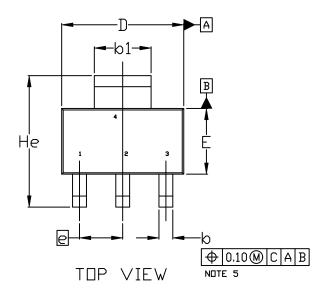
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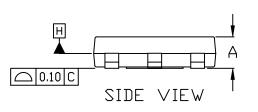
Figure 13. Safe Operating Area

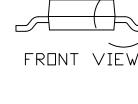


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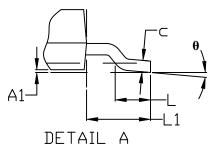
**DATE 02 OCT 2018** 







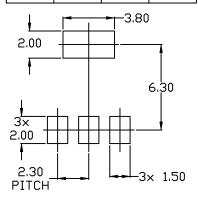
SEE DETAIL A



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLIS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
c	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
е	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10°	



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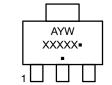
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**DATE 02 OCT 2018** 

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	4. DHAIN STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

# GENERIC MARKING DIAGRAM\*



A = Assembly Location

Y = Year W = Work Week

XXXXX = Specific Device Code

= Pb-Free Package

(Note: Microdot may be in either location)
\*This information is generic. Please refer to
device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "•", may
or may not be present. Some products may
not follow the Generic Marking.

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